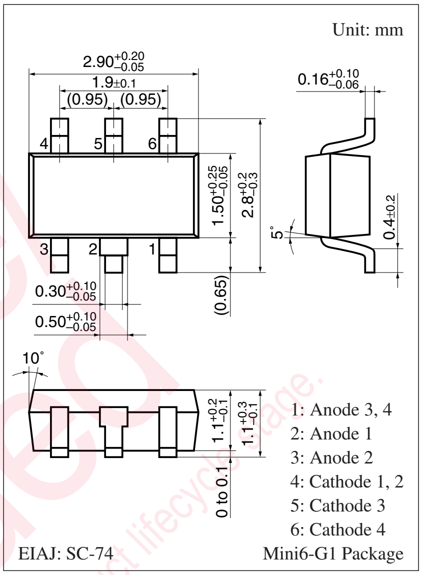
MA6X126 (MA126)

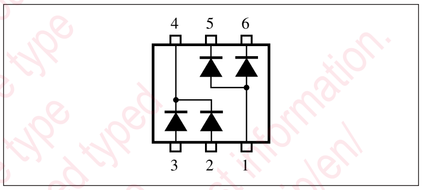
Silicon epitaxial planar type

For switching circuit



Marking Symbol: M2S

Internal Connection



■ Features

- Four isolated elements contained in one package, allowing high-density mounting
- High breakdown voltage: $V_R = 80$ V

■ Absolute Maximum Ratings $T_a = 25°C$

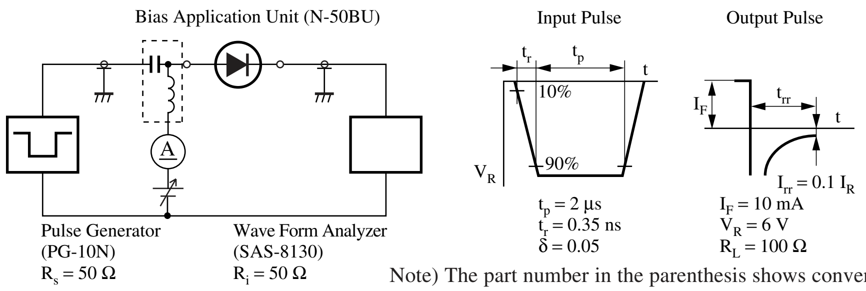
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current *1	I_F	100	mA
Peak forward current *1	I_{FM}	225	mA
Non-repetitive peak forward surge current *1, 2	I_{FSM}	500	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *1: Value for single diode
*2: t = 1 s

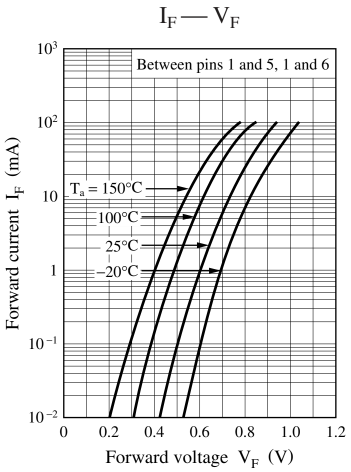
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

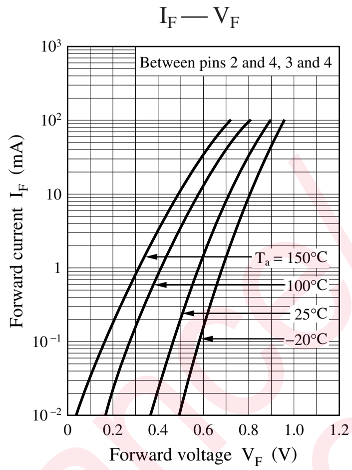
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse voltage	V_R	$I_R = 100$ μA	80			V
Reverse current	I_R	$V_R = 75$ V			100	nA
Terminal capacitance	C_{t1} *1	$V_R = 0$ V, f = 1 MHz			15	pF
	C_{t2} *2				2	
Reverse recovery time *3	t_{rr1} *1	$I_F = 10$ mA, $V_R = 6$ V			10	ns
	t_{rr2} *2	$I_{rr} = 0.1\ I_R$, $R_L = 100\ \Omega$			3	

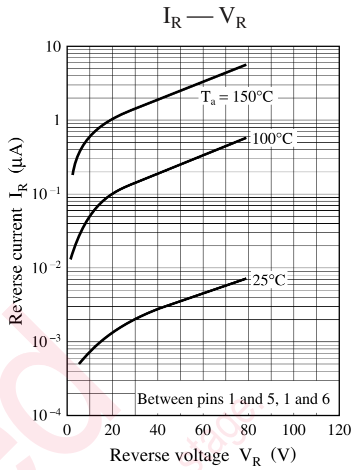
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. *1: Between pins 1 and 5, Between pins 1 and 6
*2: Between pins 4 and 2, Between pins 4 and 3
*3: t_{rr} measurement circuit

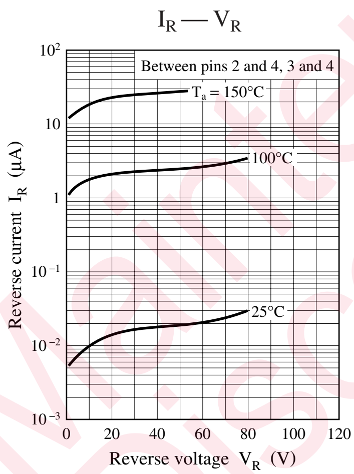


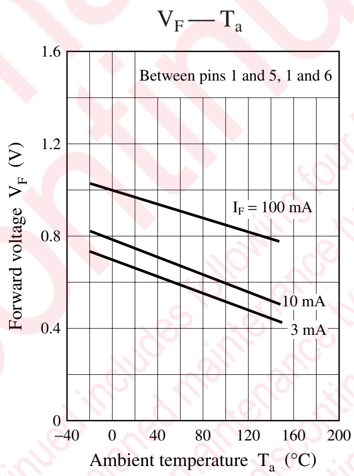
Note) The part number in the parenthesis shows conventional part number.

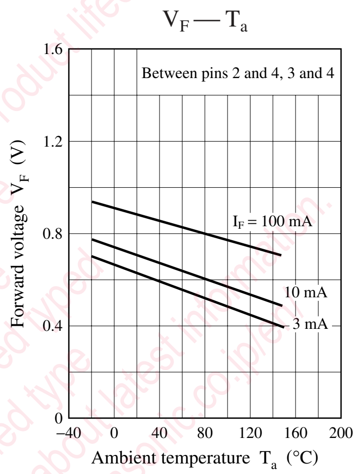


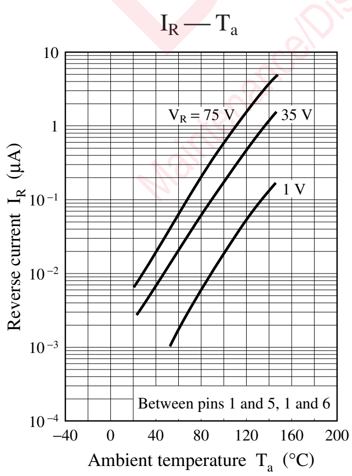


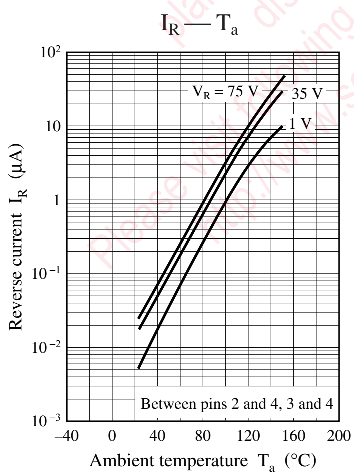


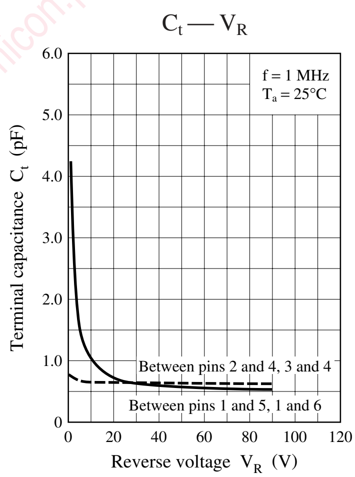




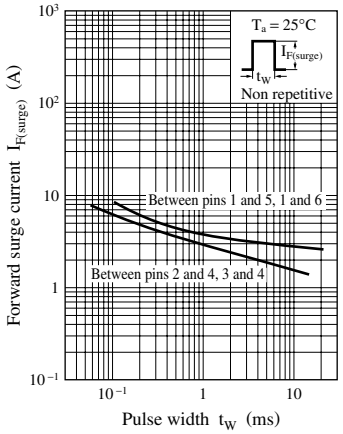








$I_{F(surge)}$ — t_W



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